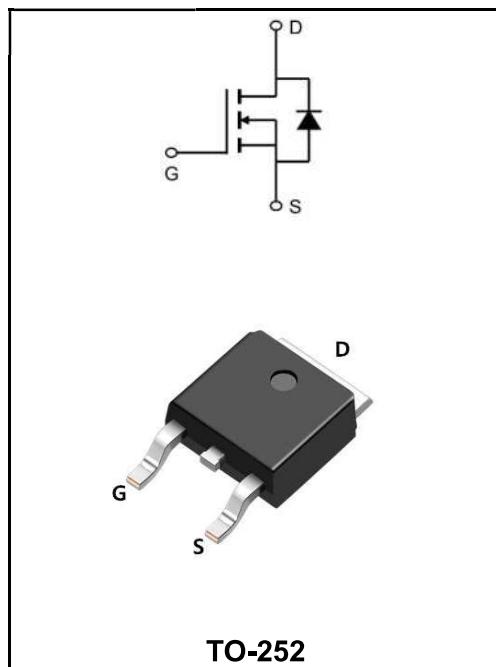


30V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	20A
V_{DSS}	30V
R_{DS(on)-typ(@V_{GS}=10V)}	< 25mΩ(Type:15.6 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW20N03AD	TO-252	YFW 20N03AD XXXXX	2500PCS/Tape

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V _{DS}	30	V
Gate - Source Voltage	V _{GS}	±20	V
Continuous Drain Current, V _{GS} @ 10V ¹ @ T _c =25°C	I _D	20	A
Continuous Drain Current, V _{GS} @ 10V ¹ @ T _c =100°C	I _D	12	A
Continuous Drain Current, V _{GS} @ 10V ¹ @ T _A =25°C	I _D	7.3	A
Continuous Drain Current, V _{GS} @ 10V ¹ @ T _A =70°C	I _D	5.8	A
Pulsed Drain Current ²	I _{DM}	50	A
Single Pulse Avalanche Energy ³	E _{AS}	8.1	mJ
Avalanche Current	I _{AS}	12.7	A
Total Power Dissipation ⁴ @ T _c =25°C	P _D	20.8	W
Total Power Dissipation ⁴ @ T _A =25°C	P _D	2	W
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	T _J	-55 to +150	°C
Thermal Resistance, Junction-Ambient ¹	R _{θJA}	62	°C/W
Thermal Resistance Junction-Case ¹	R _{θJC}	6	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	BV _{DSS}	30	32	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA	ΔBV _{DSS/ΔTJ}	-	0.023	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =10A	R _{DS(ON)}	-	15.6	25	mΩ
	V _{GS} =4.5V, I _D =8A		-	28.5	38	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	V _{GS(th)}	1.2	1.6	2.5	V
V _{GS(th)} Temperature Coefficient		ΔV _{GS(th)}	-	-4.2	-	mV/°C
Drain -Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	1	μA
	V _{DS} =24V , V _{GS} =0V , T _J =55°C		-	-	5	
Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =5V, I _D =10A	g _{FS}	-	5.5	-	S
Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	R _G	-	2.3	-	Ω
Total Gate Charge(4.5V)	V _{DS} =15V V _{GS} =4.5V I _D =10A	Q _g	-	4.9	-	nC
Gate-Source Charge		Q _{gs}	-	1.66	-	
Gate-Drain Charge		Q _{gd}	-	1.85	-	
Turn-on delay time	V _{DD} =15V V _{GS} =10V R _G =3.3 I _D =10A	t _{d(on)}	-	1.6	-	ns
Rise Time		T _r	-	15.8	-	
Turn-Off Delay Time		t _{d(OFF)}	-	13	-	
Fall Time		t _f	-	4.8	-	
Input Capacitance	V _{DS} =15V V _{GS} =0V f=1.0MHz	C _{iss}	-	216	-	pF
Output Capacitance		C _{oss}	-	62	-	
Reverse Transfer Capacitance		C _{rss}	-	51	-	
Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	I _s	-	-	24	A
Pulsed Source Current ^{2,5}		I _{SM}	-	-	50	A
Diode Forward Voltage ²	V _{GS} =0V , I _s =3A , T _J =25°C	V _{SD}	-	-	1.2	V
Reverse Recovery Time	I _F =10A , dI/dt=100A/μs , T _J =25°C	t _{rr}	-	8.7	-	ns
Reverse Recovery Charge		Q _{rr}	-	1.95	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=12.7A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

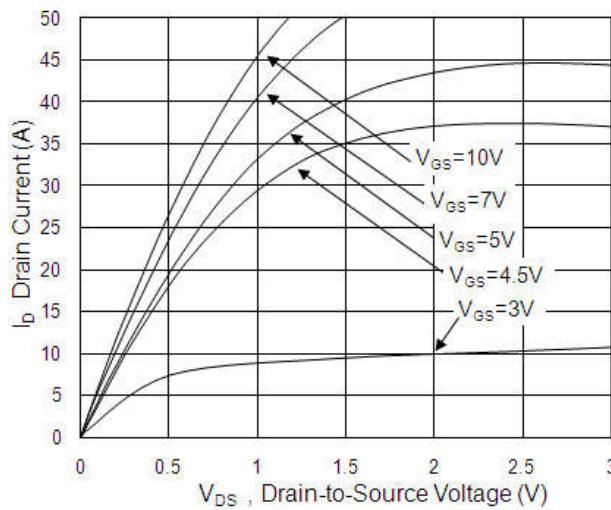


Fig.1 Typical Output Characteristics

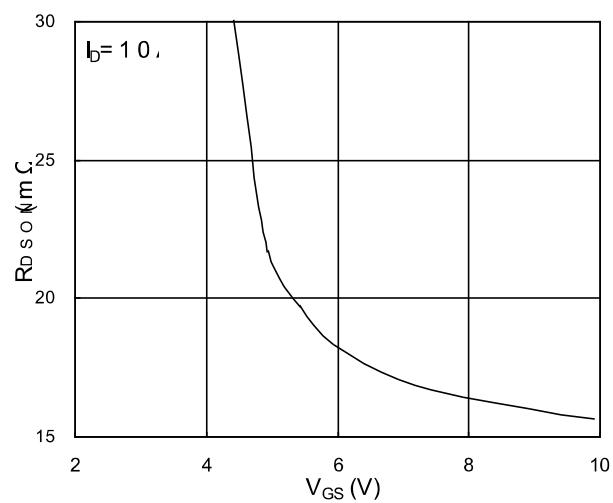


Fig.2 On-Resistance vs. Gate-Source

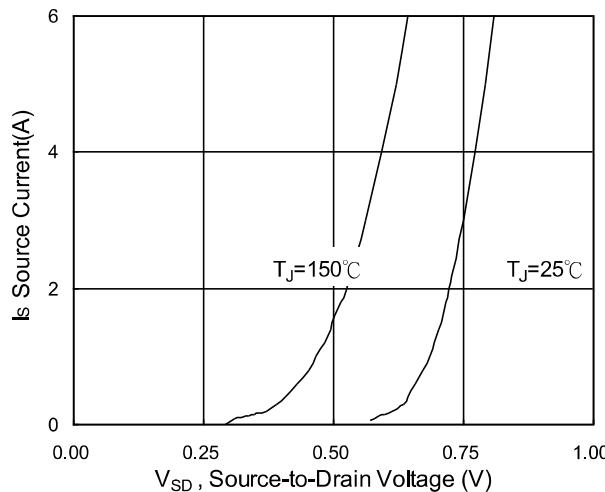


Fig.3 Forward Characteristics Of Reverse

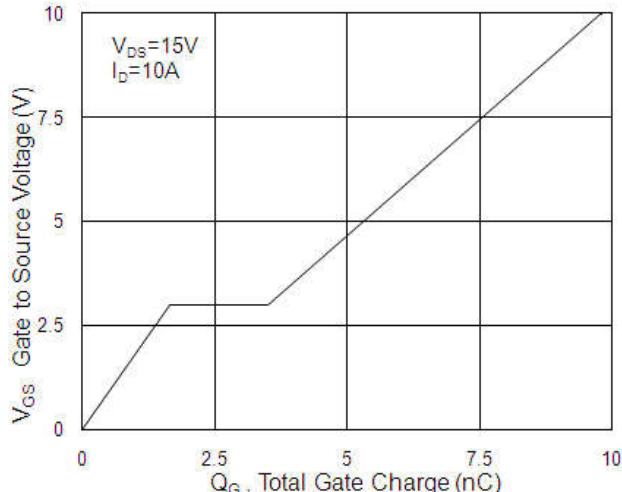


Fig.4 Gate-Charge Characteristics

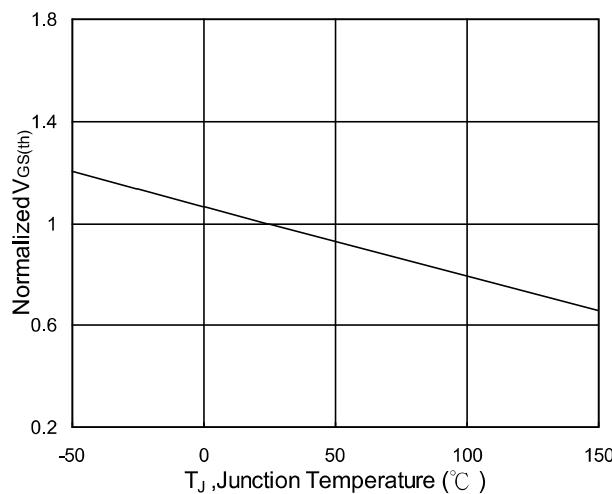


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

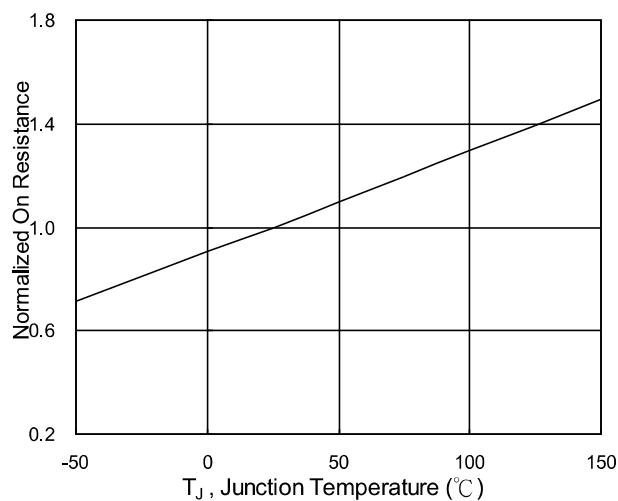


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Ratings and Characteristic Curves

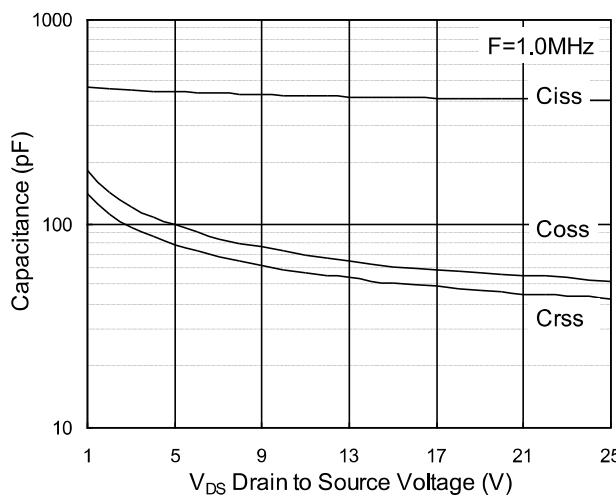


Fig.7 Capacitance

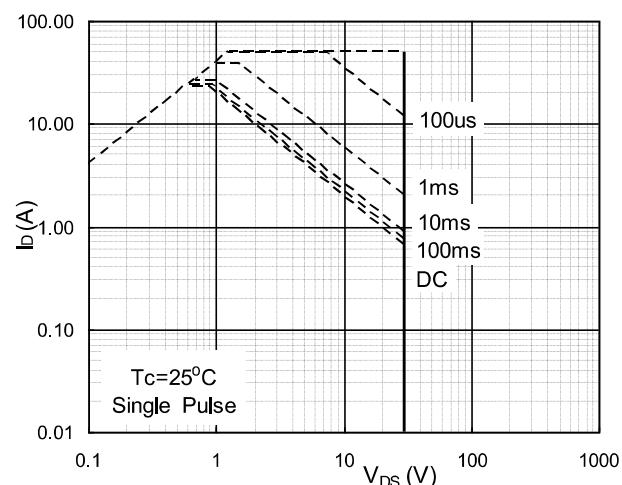


Fig.8 Safe Operating Area

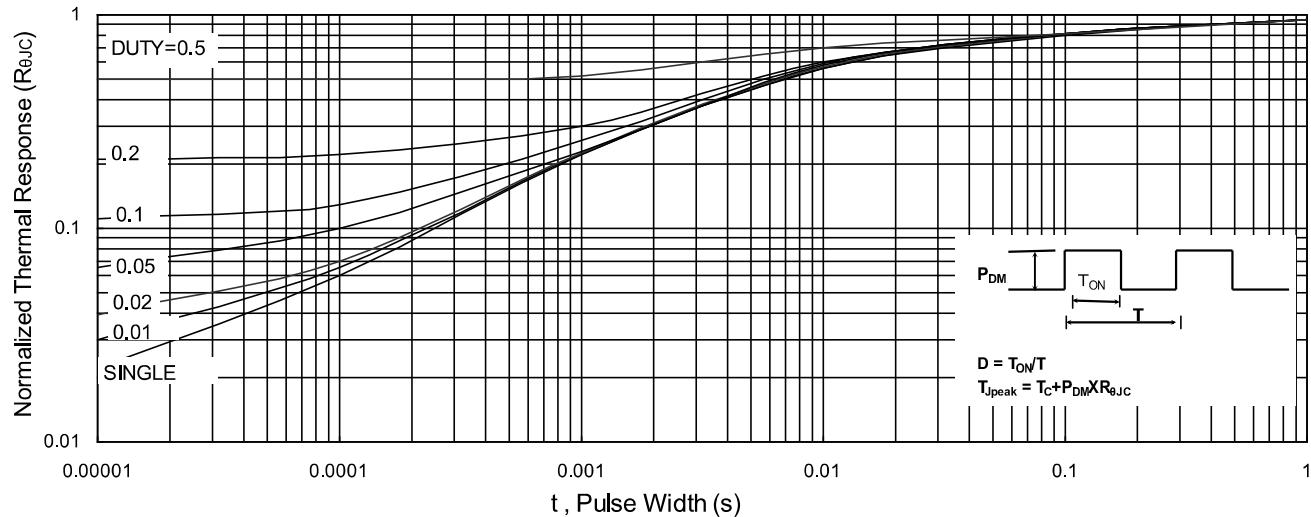


Fig.9 Normalized Maximum Transient Thermal Impedance

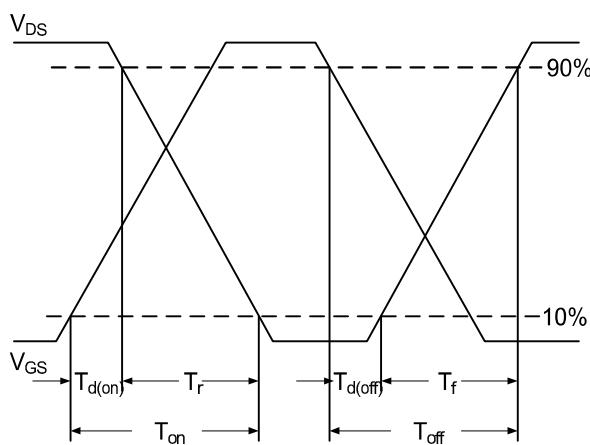


Fig.10 Switching Time Waveform

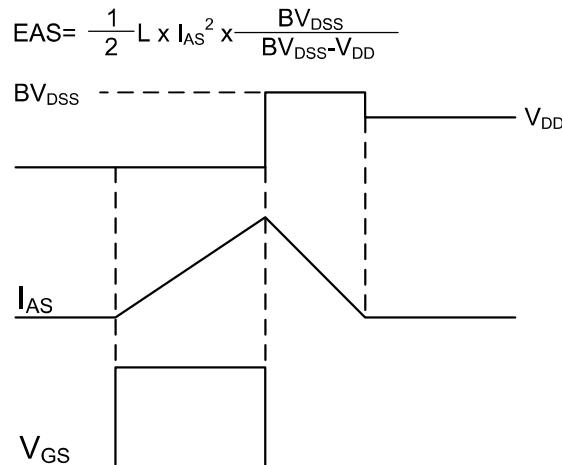


Fig.11 Unclamped Inductive Switching Waveform

Package Outline Dimensions Millimeters

TO-252

The technical drawing illustrates the physical dimensions of a TO-252 package. Key dimensions include:
 - Top View: A (height), B (width), C (lead thickness), D (lead spacing), E (lead length), F (lead width), G (lead pitch), H (total height), B2 (lead-to-body gap), and D1 (lead spacing).
 - Side View: A2 (lead height), C2 (lead width), D (lead spacing), E1 (lead thickness), and L (lead length).
 - Detail A: Shows the lead thickness V1 (7° angle), lead-to-body gap V2 (0° angle), lead length L2, and lead angle A2.

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter